SOT2034-1

WLCSP48, wafer level chip scale package, 48 terminals with gold bump, 0.15 mm pitch, 3.931 mm x 2.983 mm x 0.129 mm body

16 October 2019 Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP48
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	15-07-2019
Manufacturer package code	98ASA01416D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	3.901	3.931	3.961	mm
package width	2.953	2.983	3.013	mm
seated height	-	0.129	0.146	mm
nominal pitch	-	0.15	-	mm
actual quantity of termination	-	48	-	

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2 Package outline

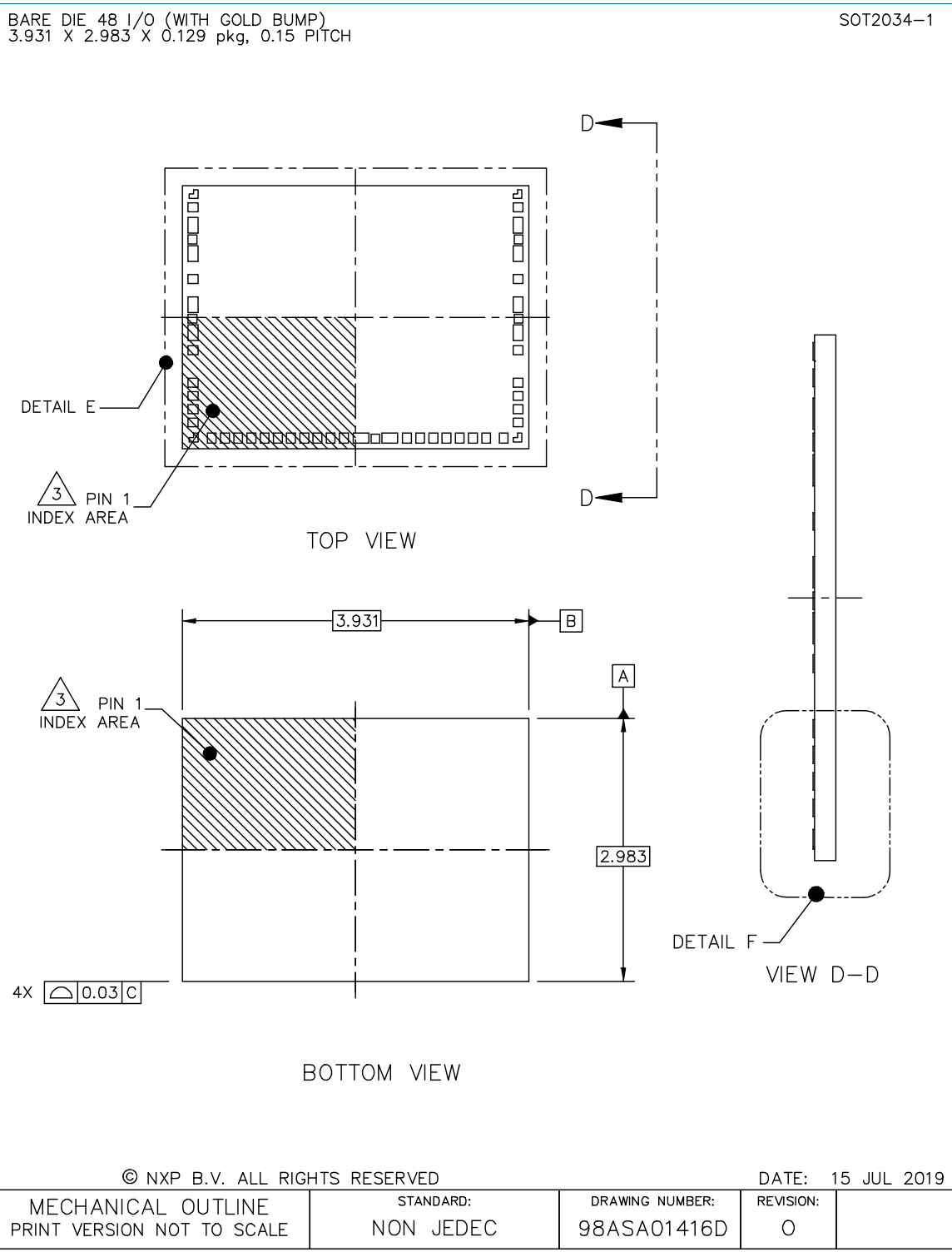

Figure 1. Package outline WLCSP48 (SOT2034-1)

WLCSP48, wafer level chip scale package, 48 terminals with gold bump, 0.15 mm pitch, 3.931 mm x 2.983 mm x 0.129 mm body

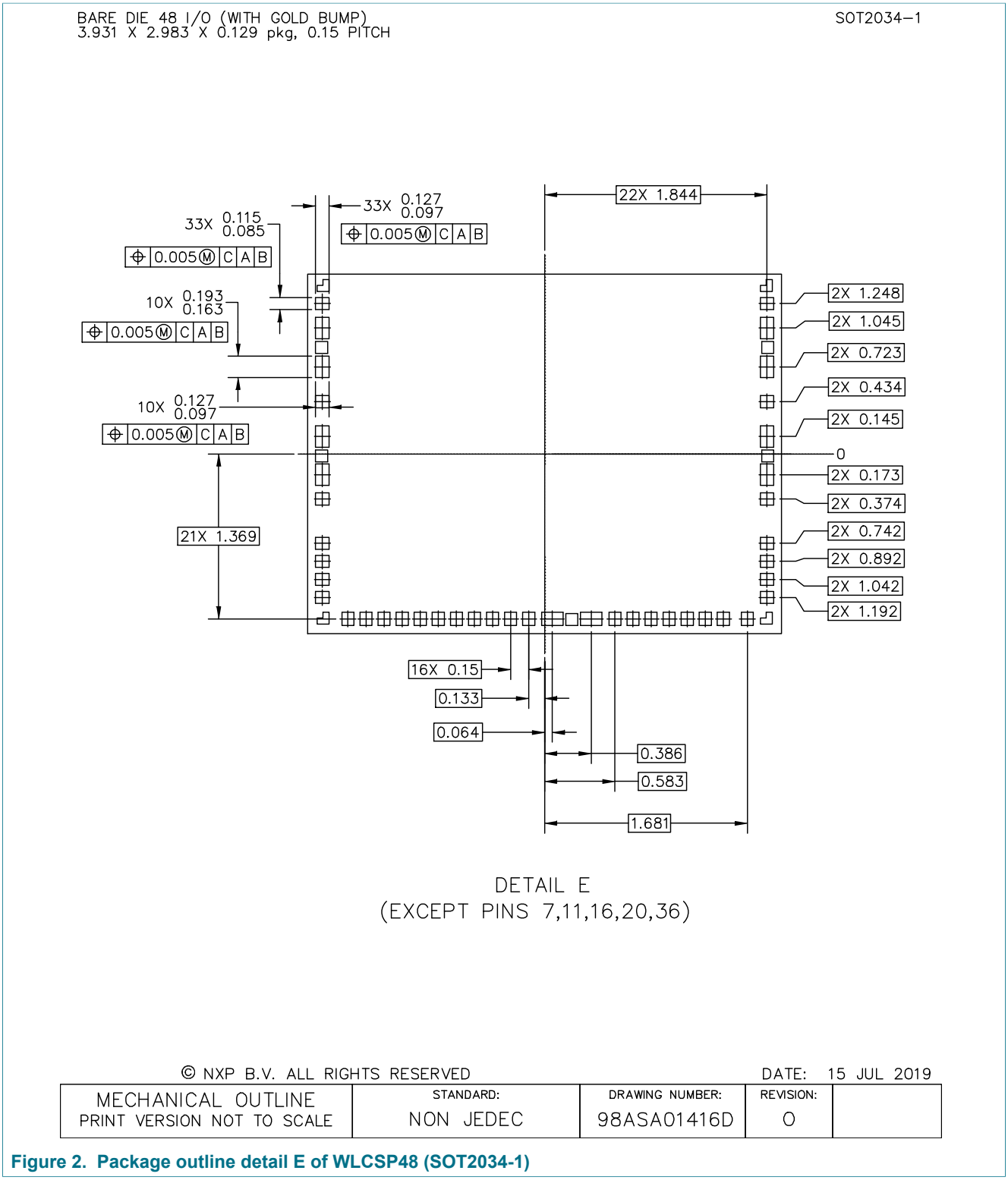

Figure 2. Package outline detail E of WLCSP48 (SOT2034-1)

WLCSP48, wafer level chip scale package, 48 terminals with gold bump, 0.15 mm pitch, 3.931 mm x 2.983 mm x 0.129 mm body

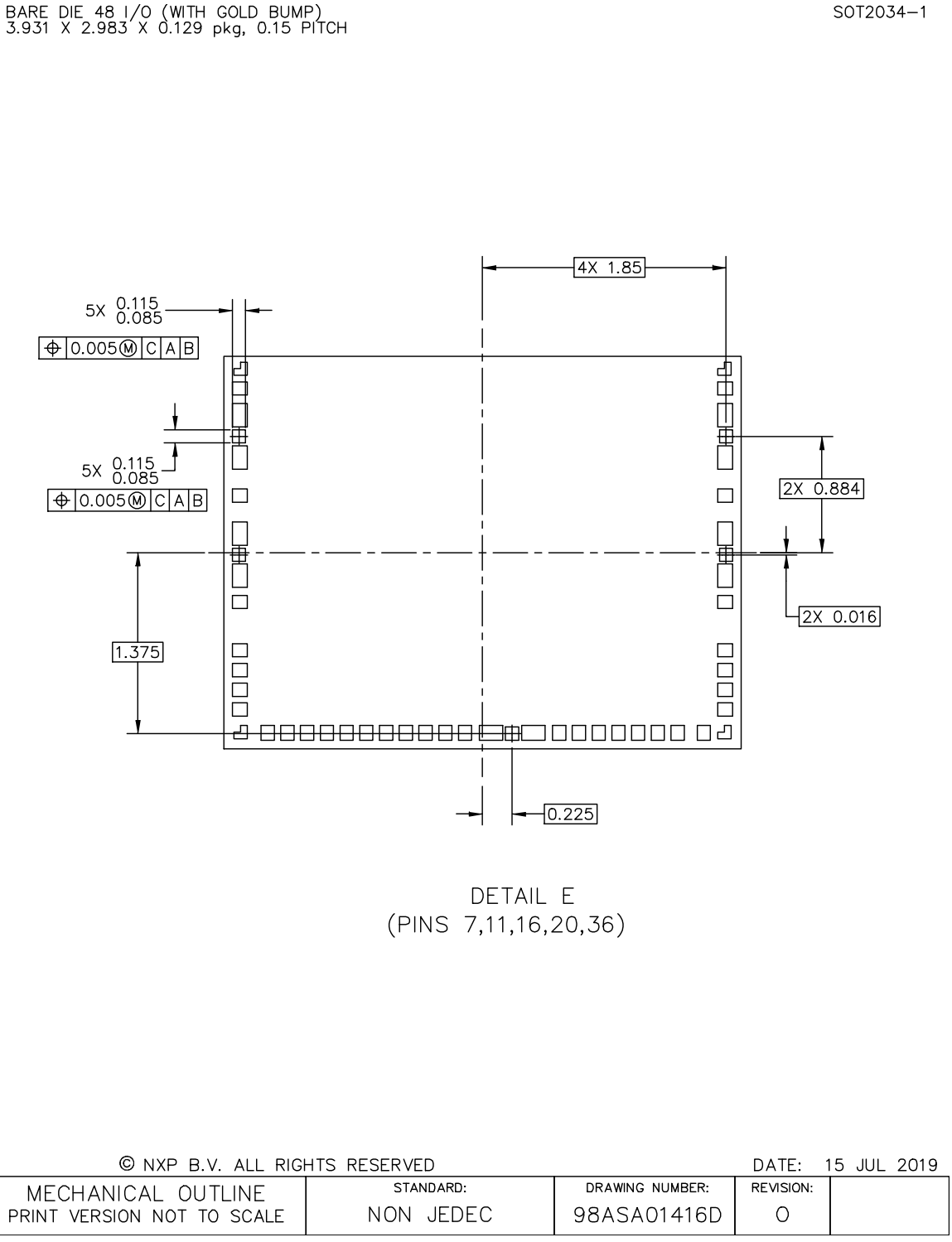

Figure 3. Package outline detail E of WLCSP48 (SOT2034-1)

WLCSP48, wafer level chip scale package, 48 terminals with gold bump, 0.15 mm pitch, 3.931 mm x 2.983 mm x 0.129 mm body

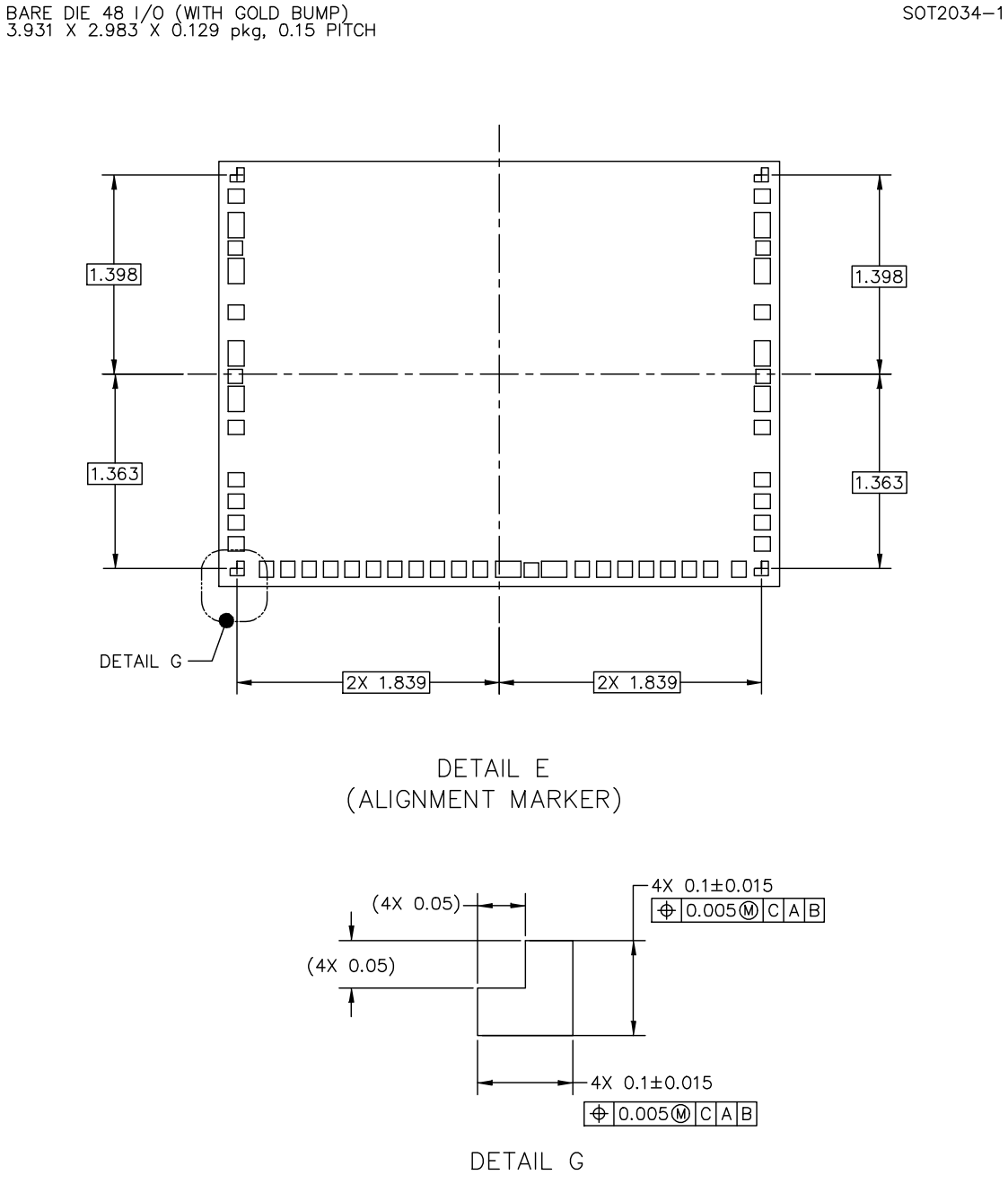

Figure 4. Package outline detail E/G of WLCSP48 (SOT2034-1)

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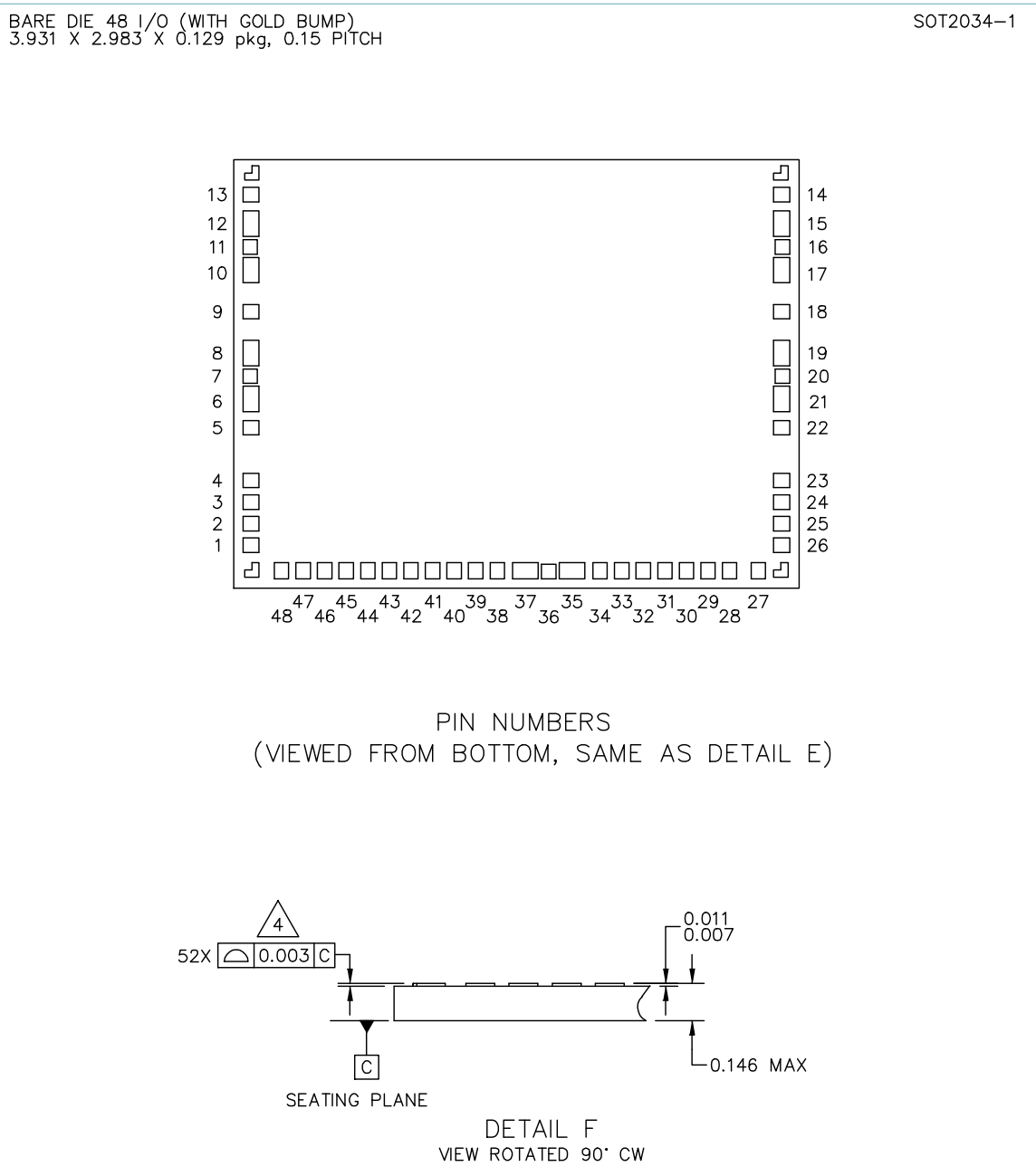

Figure 5. Package outline detail F of WLCSP48 (SOT2034-1)

WLCSP48, wafer level chip scale package, 48 terminals with gold bump, 0.15 mm pitch, 3.931 mm x 2.983 mm x 0.129 mm body

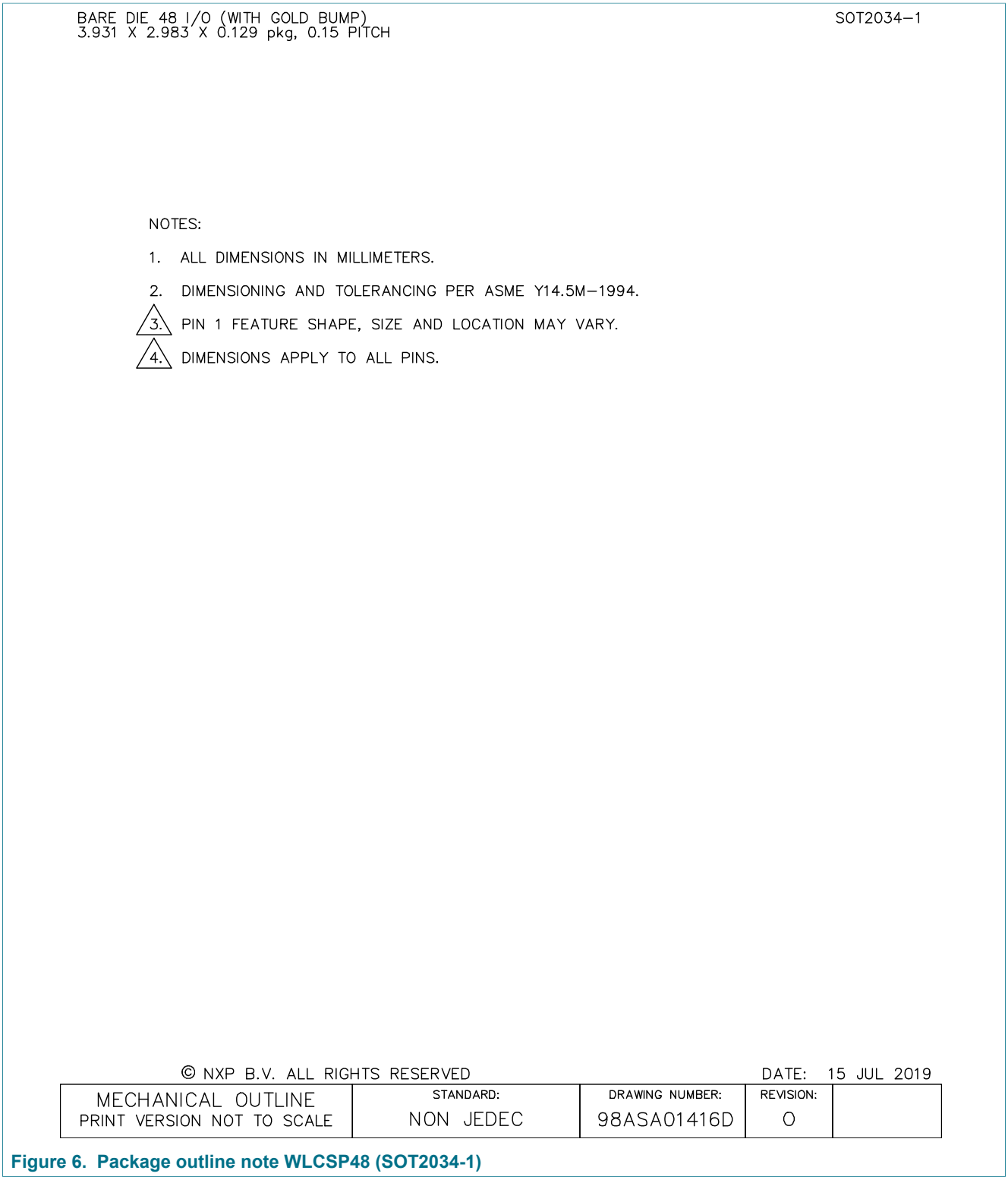

Figure 6. Package outline note WLCSP48 (SOT2034-1)

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